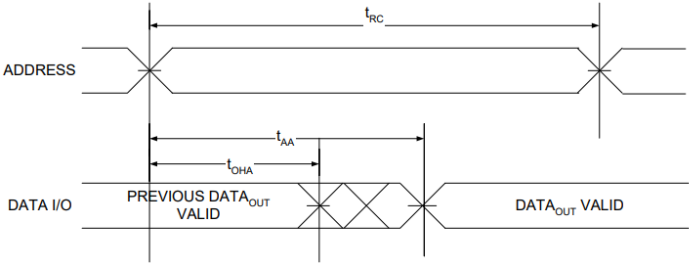


SRAM - CY7C1049G

Figure 6. Read Cycle No. 1 of CY7C1049G (Address Transition Controlled) [20, 21]



tRC = Read Cycle Time

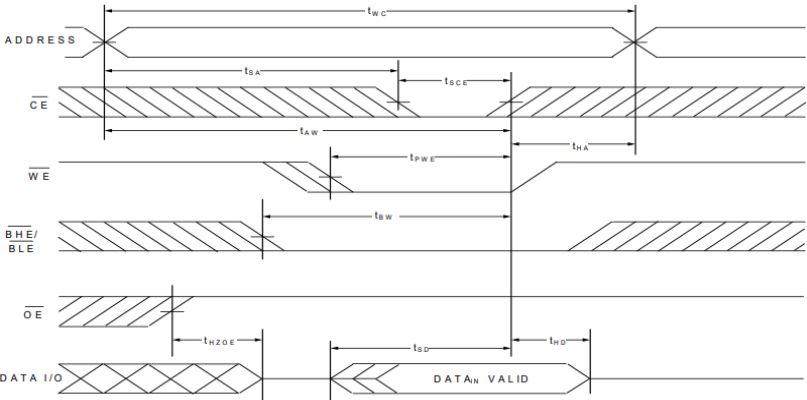
tAA = 10ns = Address to data/EER valid

$$tOHA = \text{Data} / \text{ERR hold from address change}$$

20. The device is continuously selected, OE = VIL, CE = VIL.

21. WE is HIGH for the read cycle.

Figure 9. Write Cycle No. 1 ($\overline{\text{CE}}$ Controlled) [24, 25]



t_{WC} = Write cycle time

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tSCE = CE LOW to write end
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tAW = Address setup to write end

tHA = Address hold from write end

tSA = Address setup to write start

$$tPWE = WE \text{ pulse width}$$

tHZOE = OE HIGH to HI-Z

tSD = Data setup to write end

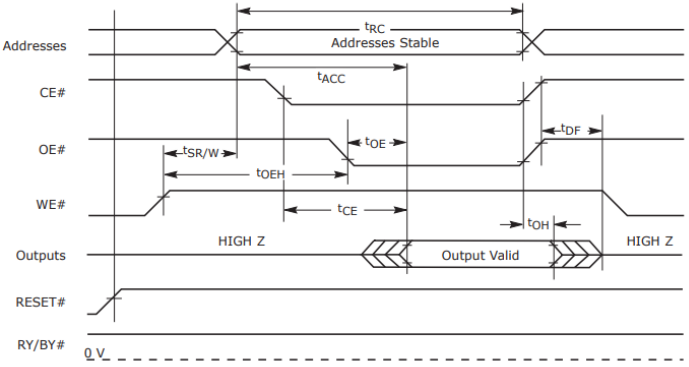
tHD = Data hold from write end

24. The internal write time of the memory is defined by the overlap of $WE = VIL$, $CE = VIL$. These signals must be LOW to initiate a write, and the HIGH transition of any of these signals can terminate the operation. The input data setup and hold timing should be referenced to the edge of the signal that terminates the write.

25. Data I/O is in HI-Z state if $\overline{\text{CE}} = \text{VIH}$, or $\text{OE} = \text{VIH}$

FLASH NOR - S29AL008J

Figure 14. Read Operations Timing



tRC = Read Cycle Time

t_{ACC} = Address to Output Delay

tCE = Chip Enable to Output Delay

tOE = Output Enable to Output Delay

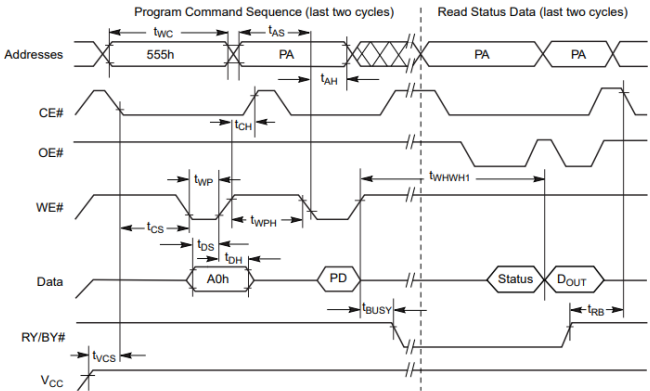
tDF = Chip or Output Enable to Output High Z

tSR/W = Latency Between Read and Write Operations

tOEH = Output Enable Hold Time

tOH = Output Hold Time From Addresses, CE# or OE#

Figure 18. Program Operation Timings



tWC = Write Cycle Time

tRB = Recovery Time from Ry/By#

tAS = Address Setup Time

tVCS = VCC Setup Time

tAH = Address Hold Time

tCH = CE# Hold Time

tWP = Write Pulse Width

tWPH1 = Programming Operation

tCS = CE# Setup Time

tWPH = Write Pulse Width High

tDS = Data Setup Time

tDH = Data Hold Time

tBUSY = Program/Erase Valid to Ry/By# Delay